



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Steinmann et al.

Art Unit: 1765

Serial No.: 09/852,921

Examiner: Deo, D.

Filing Date: 05/10/2001

Docket No.: TI-29881

Customer No.: 23494

Conf. No.: 5844

Title: METHOD OF INTEGRATING A THIN FILM RESISTOR IN A MULTI-LEVEL  
METAL TUNGSTEN-PLUG INTERCONNECT

**LETTER OF TRANSMITTAL**

Commissioner of Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents, P. O. Box 1450, Alexandria, VA 22313-1450


3-5-04  
Date

Marianna Smith  
Marianna Smith

Enclosed please find the signed Supplemental Declaration in the above-identified application.

Please charge any necessary fee to Deposit Account No. 20-0668.

Respectfully submitted,

  
Jacqueline J. Garner  
Attorney for Applicants  
Reg. No. 36,144

Texas Instruments Incorporated  
P.O. Box 655474, MS 3999  
Dallas, TX 75265  
(214)532-9348 or (972)917-5643  
Fax: (972)917-4418